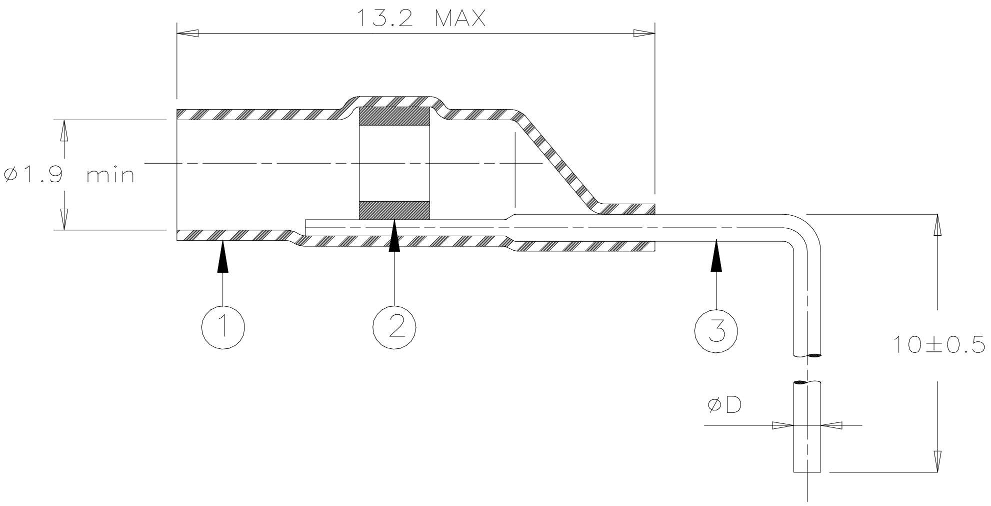
CUSTOMER DRAWING



Product Name	øD	øX
B-801-06	0.68	0.8
B-801-08	0.88	1

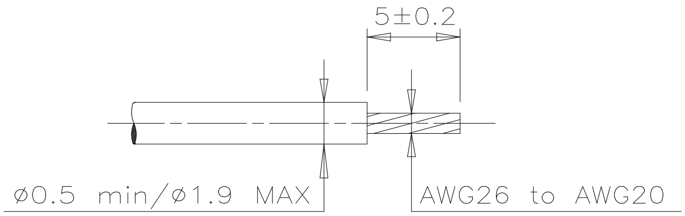
MATERIALS

1. INSULATION SLEEVE: Heat-shrinkable, transparent blue, radiation cross-linked modified polyvinylidene fluoride.
2. SOLDER PREFORM WITH FLUX:
   SOLDER: TYPE Sn62 Pb36 Ag2 per ANSI-J-STD-006.
   FLUX: TYPE ROL0 per ANSI-J-STD-004.
3. PIN: Phosphor bronze coated with Sn60 Pb40 solder alloy.

APPLICATION

1. These controlled soldering devices are designed for termination of a tin or silver plated stranded AWG26, AWG24 and AWG22 conductor having an insulation rated for at least +125°C on a PC board with øX diameter hole. If AWG20 wire is used, pre-tinning is recommended.
2. Temperature range: -55°C to +150°C. For application tooling, contact your local TE Connectivity technical service.

For best results, prepare the wire as shown:



	Raychem THERMOFIT DEVICES	TITLE: **PINPAK* DEVICE FOR PCB TERMINATION**
Unless otherwise specified dimensions are in millimeters. [Inches dimensions are shown in brackets]		DOCUMENT NO.: **B-801-0X**
TOLERANCES: 0.00 N/A 0.0 N/A 0 N/A	ANGLES: N/A ROUGHNESS IN MICRON	TE Connectivity reserves the right to amend this drawing at any time. Users should evaluate the suitability of the product for their application.
REV: 3	DATE: 09-Mar-2020	
DRAWN BY: M. FORONDA	DATE: 22-Mar-1999	ECO: ECO-20-003687
SCALE: NTS	SIZE: A	SHEET: 1 of 1

© 09-Mar-2020 Tyco Electronics Corporation. All rights reserved.
If this document is printed it becomes uncontrolled. Check for the latest revision.
*TE Connectivity, TE connectivity (logo), Raychem, THERMOFIT, SolderSleeve are trademarks